

# Very Low Supply Current 3-Pin Microprocessor Reset Monitors

## MAX809 Series, MAX810 Series

The MAX809 and MAX810 are cost-effective system supervisor circuits designed to monitor  $V_{CC}$  in digital systems and provide a reset signal to the host processor when necessary. No external components are required.

The reset output is driven active within 10  $\mu$ sec of  $V_{CC}$  falling through the reset voltage threshold. Reset is maintained active for a timeout period which is trimmed by the factory after  $V_{CC}$  rises above the reset threshold. The MAX810 has an active-high  $\overline{RESET}$  output while the MAX809 has an active-low  $\overline{RESET}$  output. Both devices are available in SOT-23 and SC-70 packages.

The MAX809/810 are optimized to reject fast transient glitches on the  $V_{CC}$  line. Low supply current of 0.5  $\mu$ A ( $V_{CC} = 3.2$  V) makes these devices suitable for battery powered applications.

### Features

- Precision  $V_{CC}$  Monitor for 1.5 V, 2.5 V, 3.0 V, 3.3 V, and 5.0 V Supplies
- Precision Monitoring Voltages from 1.2 V to 4.9 V Available in 100 mV Steps
- Four Guaranteed Minimum Power-On Reset Pulse Width Available (1 ms, 20 ms, 100 ms, and 140 ms)
- $\overline{RESET}$  Output Guaranteed to  $V_{CC} = 1.0$  V.
- Low Supply Current
- Compatible with Hot Plug Applications
- $V_{CC}$  Transient Immunity
- No External Components
- Wide Operating Temperature:  $-40^{\circ}\text{C}$  to  $105^{\circ}\text{C}$
- These Devices are Pb-Free and are RoHS Compliant

### Typical Applications

- Computers
- Embedded Systems
- Battery Powered Equipment
- Critical Microprocessor Power Supply Monitoring

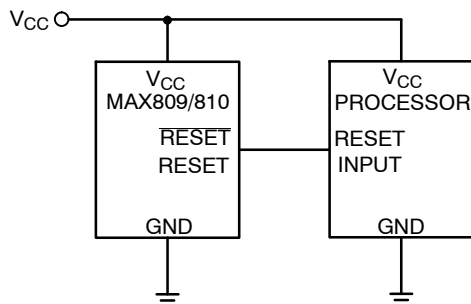
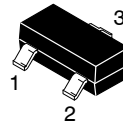
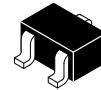
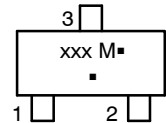


Figure 1. Typical Application Diagram

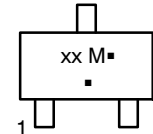
### MARKING DIAGRAMS



SOT-23  
(TO-236)  
CASE 318

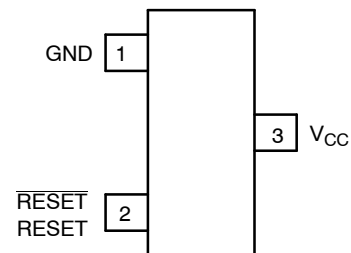


SC-70  
(SOT-323)  
CASE 419



xxx = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

### PIN CONFIGURATION



SOT-23/SC-70  
(Top View)

NOTE:  $\overline{RESET}$  is for MAX809  
RESET is for MAX810

### ORDERING INFORMATION

See detailed ordering and shipping information on page 10 of this data sheet.

### DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 10 of this data sheet.

This document contains information on some products that are still under development. onsemi reserves the right to change or discontinue these products without notice.

# MAX809 Series, MAX810 Series

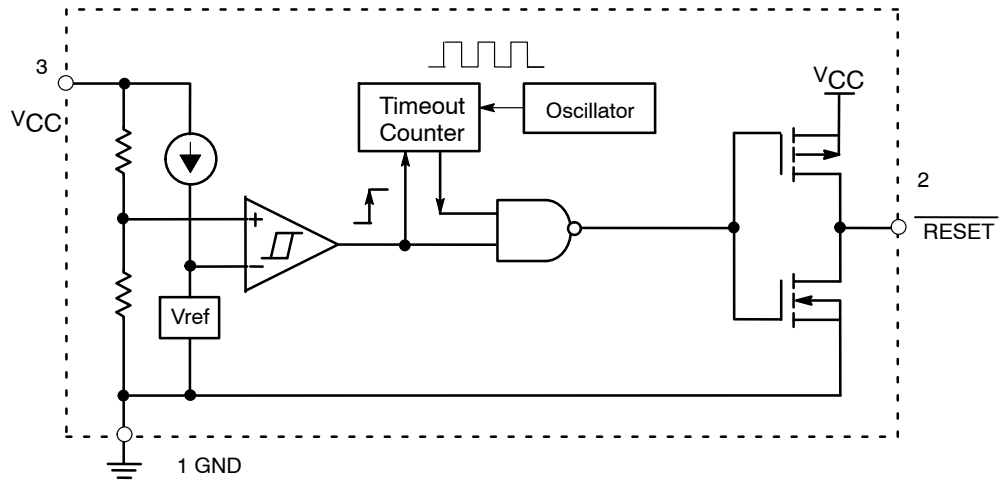


Figure 2. MAX809 Series Complementary Active-Low Output

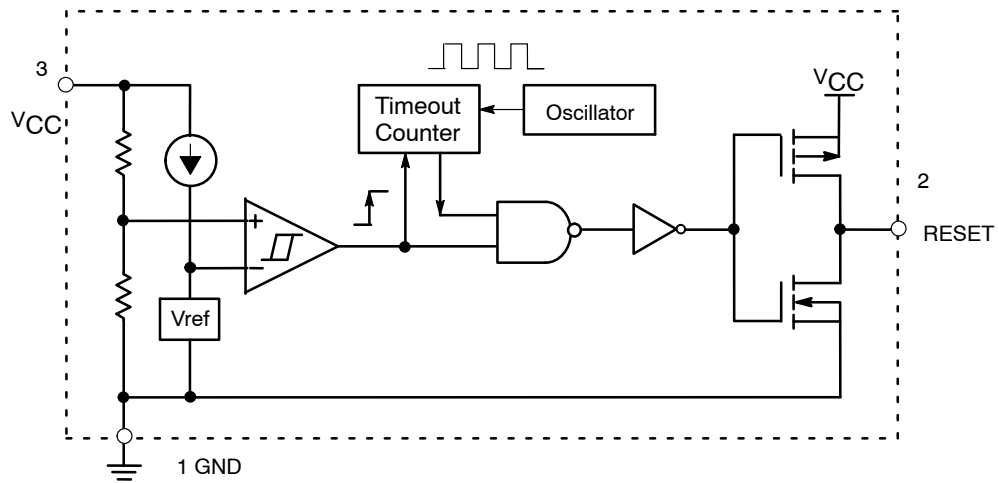


Figure 3. MAX810 Series Complementary Active-High Output

## MAX809 Series, MAX810 Series

### PIN DESCRIPTION

Pin No.	Symbol	Description
1	GND	Ground
2	RESET (MAX809)	RESET output remains low while $V_{CC}$ is below the reset voltage threshold, and for a reset timeout period after $V_{CC}$ rises above reset threshold
2	RESET (MAX810)	RESET output remains high while $V_{CC}$ is below the reset voltage threshold, and for a reset timeout period after $V_{CC}$ rises above reset threshold
3	$V_{CC}$	Supply Voltage (Typ)

### ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage ( $V_{CC}$ to GND)	$V_{CC}$	-0.3 to 6.0	V
RESET Output Voltage (CMOS)		-0.3 to ( $V_{CC} + 0.3$ )	V
Input Current, $V_{CC}$		20	mA
Output Current, $\overline{\text{RESET}}$		20	mA
dV/dt ( $V_{CC}$ )		100	V/ $\mu\text{sec}$
Thermal Resistance, Junction-to-Air (Note 1)	SOT-23 SC-70 $R_{\theta JA}$	301 314	$^{\circ}\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-40 to +125	$^{\circ}\text{C}$
Storage Temperature Range	$T_{stg}$	-65 to +150	$^{\circ}\text{C}$
Lead Temperature (Soldering, 10 Seconds)	$T_{sol}$	+260	$^{\circ}\text{C}$
ESD Protection Human Body Model (HBM): Following Specification JESD22-A114 Machine Model (MM): Following Specification JESD22-A115		2000 200	V
Latchup Current Maximum Rating: Following Specification JESD78 Class II Positive Negative	$I_{Latchup}$	200 200	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. This based on a 35x35x1.6mm FR4 PCB with 10mm<sup>2</sup> of 1 oz copper traces under natural convection conditions and a single component characterization.
2. The maximum package power dissipation limit must not be exceeded.

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}} \quad \text{with } T_{J(max)} = 150^{\circ}\text{C}$$

## MAX809 Series, MAX810 Series

**ELECTRICAL CHARACTERISTICS**  $T_A = -40^{\circ}\text{C}$  to  $+105^{\circ}\text{C}$  unless otherwise noted. Typical values are at  $T_A = +25^{\circ}\text{C}$ . (Note 3)

Characteristic	Symbol	Min	Typ	Max	Unit
$V_{CC}$ Range $T_A = 0^{\circ}\text{C}$ to $+70^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 4)		1.0 1.2	– –	5.5 5.5	V
Supply Current $V_{CC} = 3.3\text{ V}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = 85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5) $V_{CC} = 5.5\text{ V}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = 85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)	$I_{CC}$	– –	0.5 –	1.2 2.0	$\mu\text{A}$
Reset Threshold ( $V_{in}$ Decreasing) (Note 6)	$V_{TH}$				V
MAX809SN490 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		4.83 4.78 4.66	4.9 – –	4.97 5.02 5.14	
MAX8xxLTR, MAX8xxSQ463 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		4.56 4.50 4.40	4.63 – –	4.70 4.75 4.86	
MAX809HTR $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		4.48 4.43 4.32	4.55	4.62 4.67 4.78	
MAX8xxMTR, MAX8xxSQ438 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		4.31 4.27 4.16	4.38	4.45 4.49 4.60	
MAX809JTR, MAX8xxSQ400 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		3.94 3.90 3.80	4.00 – –	4.06 4.10 4.20	
MAX8xxTTR, MAX809SQ308 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		3.04 3.00 2.92	3.08 – –	3.11 3.16 3.24	
MAX8xxSTR, MAX8xxSQ293 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		2.89 2.85 2.78	2.93 – –	2.96 3.00 3.08	
MAX8xxRTR, MAX8xxSQ263 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		2.59 2.56 2.49	2.63 – –	2.66 2.70 2.77	
MAX809SN232, MAX809SQ232 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		2.28 2.25 2.21	2.32 – –	2.35 2.38 2.45	
MAX809SN160 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		1.58 1.56 1.52	1.60 – –	1.62 1.64 1.68	
MAX809SN120, MAX8xxSQ120 $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ (Note 5)		1.18 1.17 1.14	1.20 – –	1.22 1.23 1.26	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Production testing done at  $T_A = 25^{\circ}\text{C}$ , over temperature limits guaranteed by design.
4. For NCV automotive devices, this temperature range is  $T_A = -40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ .
5. For NCV automotive devices, this temperature range is  $T_A = +85^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ .
6. Contact your **onsemi** sales representative for other threshold voltage options.

## MAX809 Series, MAX810 Series

**ELECTRICAL CHARACTERISTICS (continued)**  $T_A = -40^{\circ}\text{C}$  to  $+105^{\circ}\text{C}$  unless otherwise noted. Typical values are at  $T_A = +25^{\circ}\text{C}$ . (Note 7)

Characteristic	Symbol	Min	Typ	Max	Unit
Detector Voltage Threshold Temperature Coefficient		–	30	–	ppm/ $^{\circ}\text{C}$
$V_{CC}$ to Reset Delay $V_{CC} = V_{TH}$ to $(V_{TH} - 100\text{ mV})$		–	10	–	$\mu\text{sec}$
Reset Active TimeOut Period (Note 8) MAX8xxSN(Q)293D1 MAX8xxSN(Q)293D2 MAX8xxSN(Q)293D3 MAX8xxSN(Q)293	$t_{RP}$	1.0 20 100 140	– – – –	3.3 66 330 460	msec
RESET Output Voltage Low (No Load) (MAX809) $V_{CC} = V_{TH} - 0.2\text{ V}$ $1.6\text{ V} \leq V_{TH} \leq 2.0\text{ V}$ , $I_{SINK} = 0.5\text{ mA}$ $2.1\text{ V} \leq V_{TH} \leq 4.0\text{ V}$ , $I_{SINK} = 1.2\text{ mA}$ $4.1\text{ V} \leq V_{TH} \leq 4.9\text{ V}$ , $I_{SINK} = 3.2\text{ mA}$	$V_{OL}$	–	–	0.3	V
RESET Output Voltage High (No Load) (MAX809) $V_{CC} = V_{TH} + 0.2\text{ V}$ $1.6\text{ V} \leq V_{TH} \leq 2.4\text{ V}$ , $I_{SOURCE} = 200\text{ }\mu\text{A}$ $2.5\text{ V} \leq V_{TH} \leq 4.9\text{ V}$ , $I_{SOURCE} = 500\text{ }\mu\text{A}$	$V_{OH}$	$0.8 V_{CC}$	–	–	V
RESET Output Voltage High (No Load) (MAX810) $V_{CC} = V_{TH} - 0.2\text{ V}$ $1.6\text{ V} \leq V_{TH} \leq 2.4\text{ V}$ , $I_{SOURCE} = 200\text{ }\mu\text{A}$ $2.5\text{ V} \leq V_{TH} \leq 4.9\text{ V}$ , $I_{SOURCE} = 500\text{ }\mu\text{A}$	$V_{OH}$	$0.8 V_{CC}$	–	–	V
RESET Output Voltage Low (No Load) (MAX810) $V_{CC} = V_{TH} + 0.2\text{ V}$ $1.6\text{ V} \leq V_{TH} \leq 2.0\text{ V}$ , $I_{SINK} = 0.5\text{ mA}$ $2.1\text{ V} \leq V_{TH} \leq 4.0\text{ V}$ , $I_{SINK} = 1.2\text{ mA}$ $4.1\text{ V} \leq V_{TH} \leq 4.9\text{ V}$ , $I_{SINK} = 3.2\text{ mA}$	$V_{OL}$	–	–	0.3	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

7. Production testing done at  $T_A = 25^{\circ}\text{C}$ , over temperature limits guaranteed by design.

8. Contact your **onsemi** sales representative for timeout options availability for other threshold voltage options.

# MAX809 Series, MAX810 Series

## TYPICAL OPERATING CHARACTERISTICS

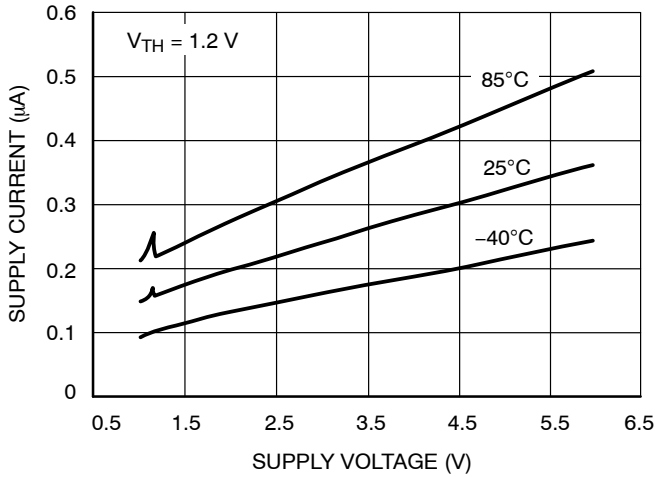


Figure 4. Supply Current vs. Supply Voltage

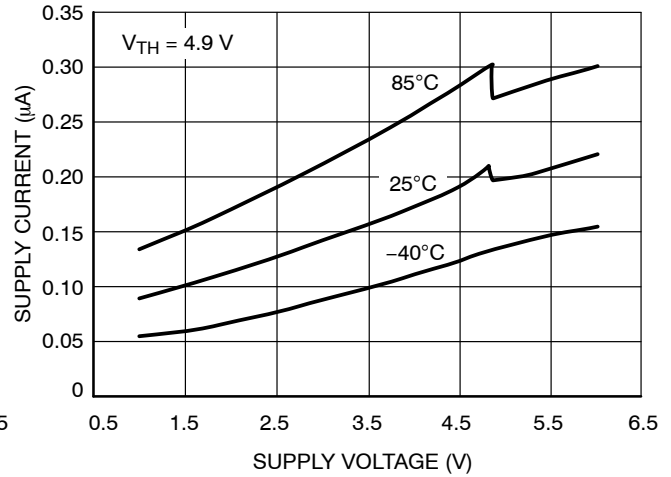


Figure 5. Supply Current vs. Supply Voltage

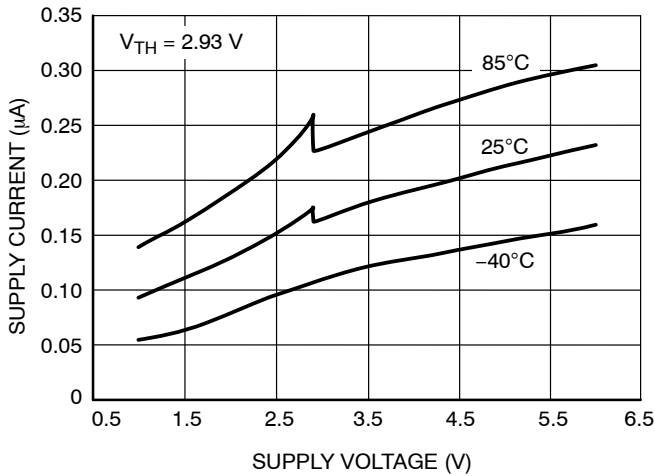


Figure 6. Supply Current vs. Supply Voltage

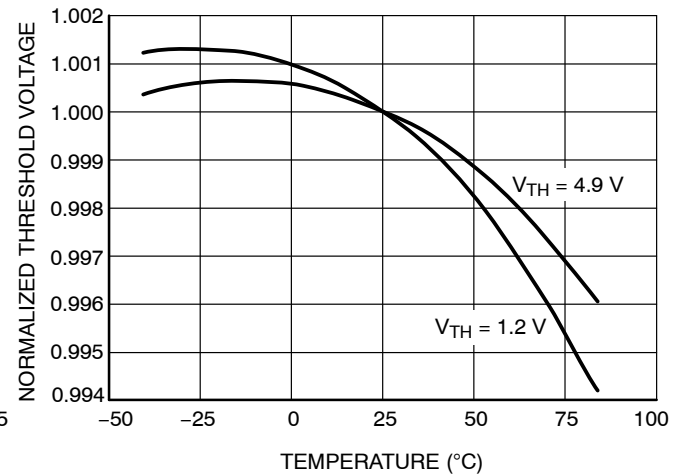


Figure 7. Normalized Reset Threshold Voltage vs. Temperature

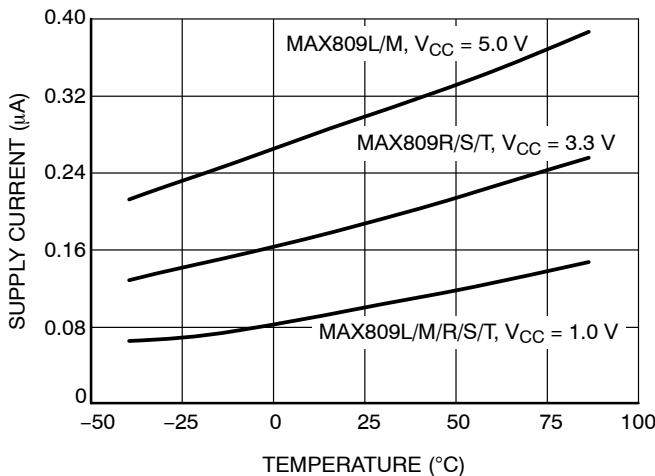


Figure 8. Supply Current vs. Temperature (No Load, MAX809)

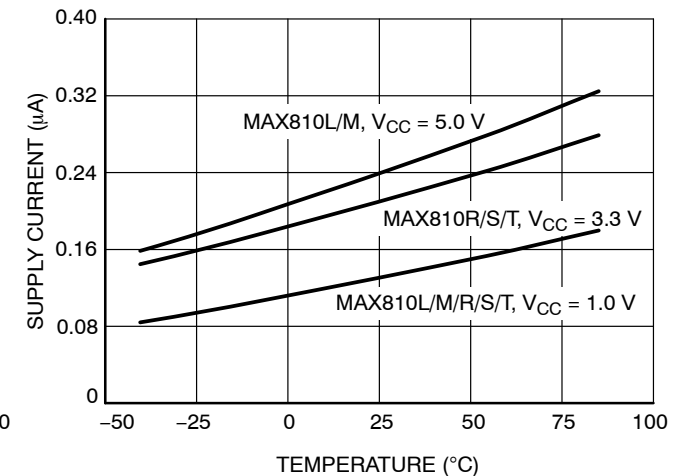
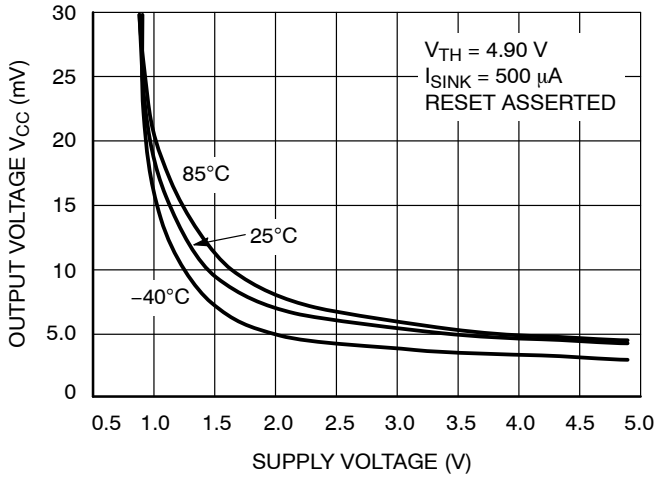


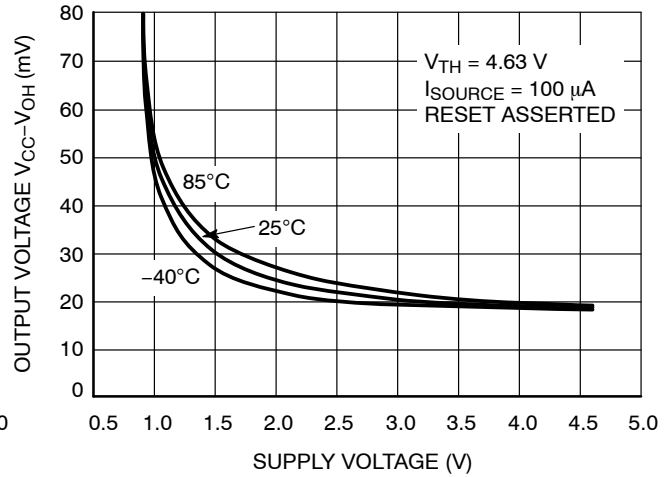
Figure 9. Supply Current vs. Temperature (No Load, MAX810)

# MAX809 Series, MAX810 Series

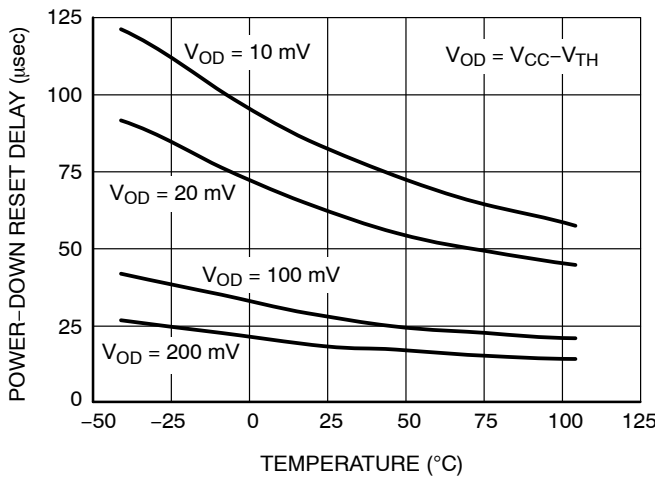
## TYPICAL OPERATING CHARACTERISTICS



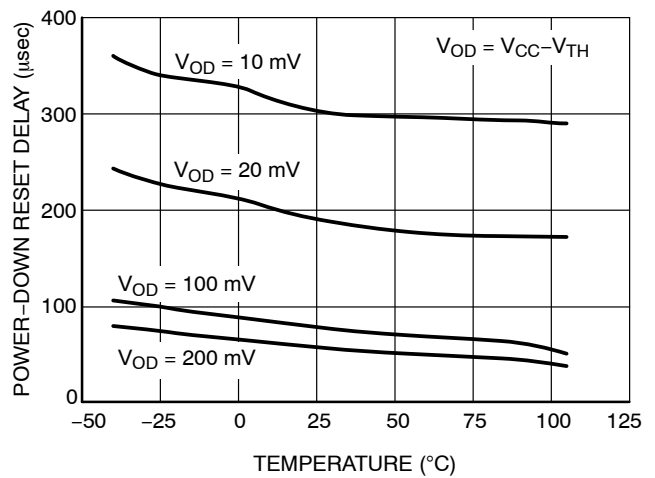
**Figure 10. Output Voltage Low vs. Supply Voltage**



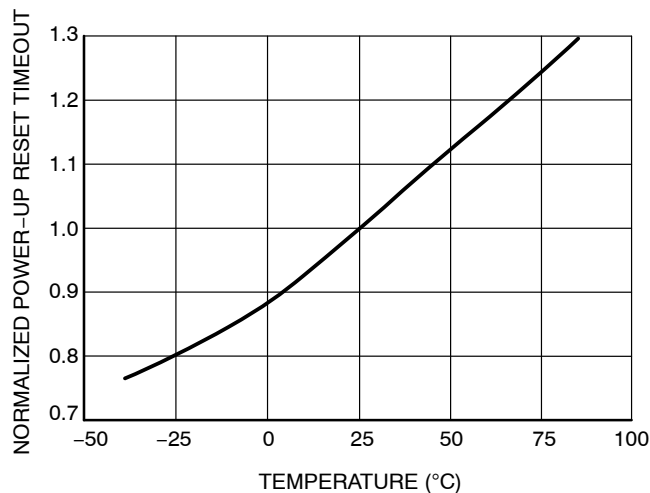
**Figure 11. Output Voltage High vs. Supply Voltage**



**Figure 12. Power-Down Reset Delay vs. Temperature and Overdrive ( $V_{TH} = 1.2 V$ )**



**Figure 13. Power-Down Reset Delay vs. Temperature and Overdrive ( $V_{TH} = 4.9 V$ )**



**Figure 14. Normalized Power-Up Reset vs. Temperature**

## MAX809 Series, MAX810 Series

### Detail Operation Description

The MAX809/810 series microprocessor reset supervisory circuits are designed to monitor the power supplies in digital systems and provide a reset signal to the processor without any external components. Figure 2 shows the timing diagram and a typical application below. Initially consider that input voltage  $V_{CC}$  is at a nominal level greater than the voltage detector upper threshold ( $V_{TH+}$ ). And the  $\overline{\text{RESET}}$  (RESET) output voltage (Pin 2) will be in the high state for MAX809, or in the low state for MAX 810 devices.

If there is an input power interruption and  $V_{CC}$  becomes significantly deficient, it will fall below the lower detector threshold ( $V_{TH-}$ ). This event causes the RESET output to be in the low state for the MAX809, or in the high state for the NCP810 devices. After completion of the power interruption,  $V_{CC}$  will rise to its nominal level and become greater than the  $V_{TH}$ . This sequence activates the internal oscillator circuitry and digital counter to count. After the count of the timeout period, the reset output will revert back to the original state.

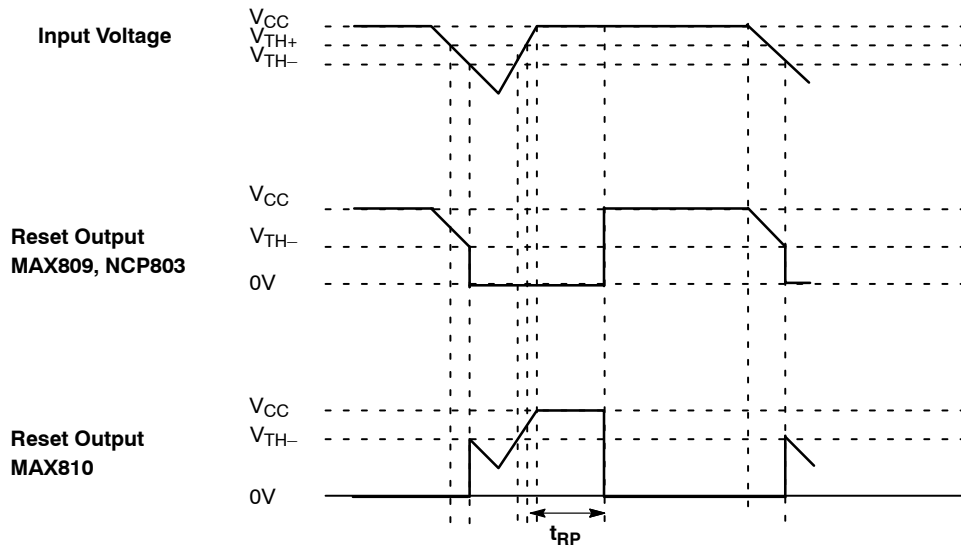


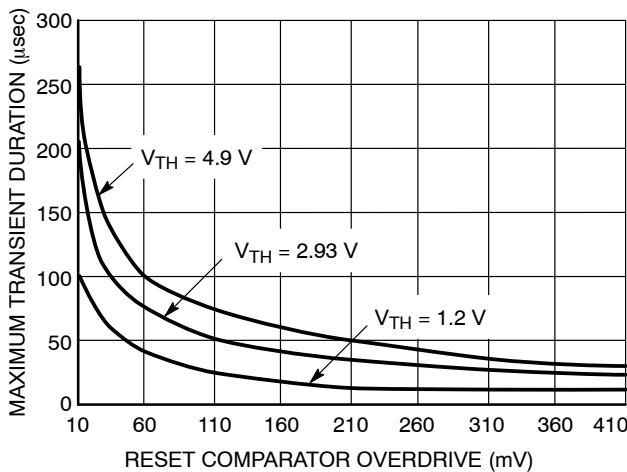
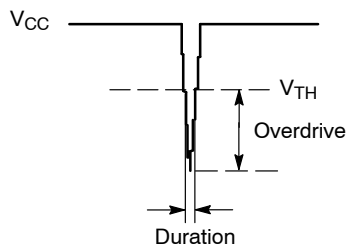
Figure 15. Timing Waveforms



## APPLICATIONS INFORMATION

### V<sub>CC</sub> Transient Rejection

The MAX809 provides accurate V<sub>CC</sub> monitoring and reset timing during power-up, power-down, and brownout/sag conditions, and rejects negative-going transients (glitches) on the power supply line. Figure 16 shows the maximum transient duration vs. maximum negative excursion (overdrive) for glitch rejection. Any combination of duration and overdrive which lies **under** the curve will **not** generate a reset signal. Combinations above the curve are detected as a brownout or power-down. Typically, transient that goes 100 mV below the reset threshold and lasts 5.0 μs or less will not cause a reset pulse. Transient immunity can be improved by adding a capacitor in close proximity to the V<sub>CC</sub> pin of the MAX809.

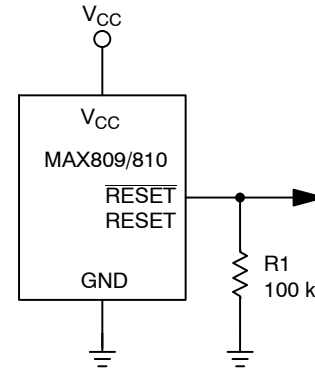


**Figure 16. Maximum Transient Duration vs. Overdrive for Glitch Rejection at 25°C**

### RESET Signal Integrity During Power-Down

The MAX809 RESET output is valid to V<sub>CC</sub> = 1.0 V. Below this voltage the output becomes an “open circuit” and does not sink current. This means CMOS logic inputs to the Microprocessor will be floating at an undetermined voltage. Most digital systems are completely shutdown well above this voltage. However, in situations where RESET must be

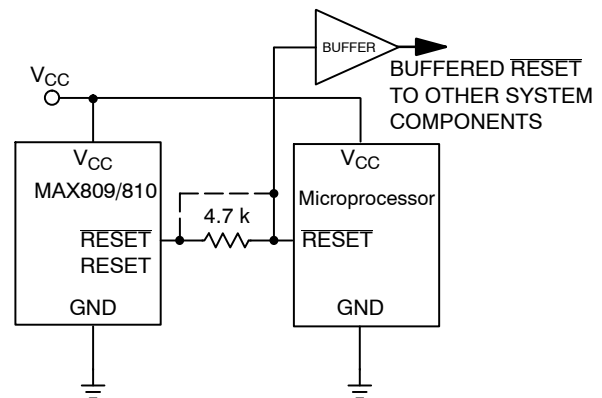
maintained valid to V<sub>CC</sub> = 0 V, a pull-down resistor must be connected from RESET to ground to discharge stray capacitances and hold the output low (Figure 17). This resistor value, though not critical, should be chosen such that it does not appreciably load RESET under normal operation (100 kΩ will be suitable for most applications).



**Figure 17. Ensuring RESET Valid to V<sub>CC</sub> = 0 V**

### Processors With Bidirectional I/O Pins

Some Microprocessor's have bidirectional reset pins. Depending on the current drive capability of the processor pin, an indeterminate logic level may result if there is a logic conflict. This can be avoided by adding a 4.7 kΩ resistor in series with the output of the MAX809 (Figure 18). If there are other components in the system which require a reset signal, they should be buffered so as not to load the reset line. If the other components are required to follow the reset I/O of the Microprocessor, the buffer should be connected as shown with the solid line.



**Figure 18. Interfacing to Bidirectional Reset I/O**

## MAX809 Series, MAX810 Series

### ORDERING, MARKING AND THRESHOLD INFORMATION

Part Number	V <sub>TH</sub> * (V)	Timeout* (ms)	Description	Marking	Package	Shipping†		
MAX809SN160T1G	1.60	140–460	Push–Pull RESET	SAA	SOT23–3 (Pb–Free)	3000 / Tape & Reel		
MAX809SN232T1G	2.32	140–460		SQP				
MAX809RTRG	2.63	140–460		SPS				
NCV809RTRG	2.63	140–460		RPA				
MAX809STRG	2.93	140–460		SPT				
NCV809STRG	2.93	140–460		SUC				
MAX809TTRG	3.08	140–460		SPU				
MAX809JTRG	4.00	140–460		SPR				
MAX809MTRG	4.38	140–460		SPV				
NCV809MTRG	4.38	140–460		TAT				
MAX809HTRG	4.55	140–460		SBD				
MAX809LTRG	4.63	140–460		SPW				
NCV809LTRG	4.63	140–460		STA				
MAX809SN490T1G	4.90	140–460		SBH				
MAX809SN120T1G	1.20	140–460		SSO				
MAX809SN293D1T1G	2.93	1–3.3		SSP				
NCV809SN293D1T1G*				ACT				
MAX809SN293D2T1G	2.93	20–66		SSQ				
NCV809SN293D2T1G	2.93	20–66		ACE				
MAX809SN293D3T1G	2.93	100–330		SSR				
MAX809SQ120T1G	1.20	140–460		ZD			SC70–3 (Pb–Free)	3000 / Tape & Reel
MAX809SQ232T1G	2.32	140–460		ZE				
MAX809SQ263T1G	2.63	140–460		ZF				
MAX809SQ293T1G	2.93	140–460		ZG				
NCV809SQ293T1G* (In Development)								
MAX809SQ308T1G	3.08	140–460		ZH				
MAX809SQ400T1G	4.00	140–460		SZ				
MAX809SQ438T1G	4.38	140–460		ZI				
MAX809SQ463T1G	4.63	140–460	ZJ					
MAX809SQ293D1T1G	2.93	1–3.3	ZK					
MAX809SQ293D2T1G	2.93	20–66	ZL					
MAX809SQ293D3T1G	2.93	100–330	ZM					

## MAX809 Series, MAX810 Series

### ORDERING, MARKING AND THRESHOLD INFORMATION

Part Number	V <sub>TH</sub> ** (V)	Timeout** (ms)	Description	Marking	Package	Shipping†
MAX810RTRG	2.63	140–460	Push–Pull <b>RESET</b>	SPX	SOT23–3 (Pb–Free)	3000 / Tape & Reel
MAX810STRG	2.93	140–460		SPY		
MAX810TTRG	3.08	140–460		SPZ		
MAX810MTRG	4.38	140–460		SQA		
MAX810LTRG	4.63	140–460		SQB		
MAX810SN120T1G	1.20	140–460		SSS		
MAX810SN293D1T1G	2.93	1–3.3		SST		
MAX810SN293D2T1G	2.93	20–66		SSU		
MAX810SN293D3T1G	2.93	100–330		SSZ		
MAX810SQ120T1G	1.20	140–460		ZN	SC70–3 (Pb–Free)	3000 / Tape & Reel
MAX810SQ263T1G	2.63	140–460		ZO		
MAX810SQ270T1G	2.70	20–66		ZB		
MAX810SQ293T1G	2.93	140–460		ZP		
MAX810SQ400T1G	4.00	20–66		ZC		
MAX810SQ438T1G	4.38	140–460		ZQ		
MAX810SQ463T1G	4.63	140–460		ZR		
MAX810SQ293D1T1G	2.93	1–3.3		ZS		
MAX810SQ293D2T1G	2.93	20–66		ZT		
MAX810SQ293D3T1G	2.93	100–330		ZU		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

\*\*Contact your **onsemi** sales representative for other threshold voltage options.

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

## SC-70 (SOT-323) CASE 419 ISSUE R

DATE 11 OCT 2022



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH

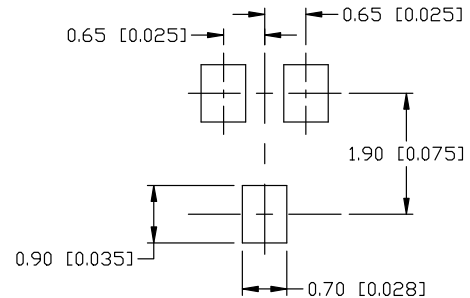
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.080	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
H <sub>E</sub>	2.00	2.10	2.40	0.079	0.083	0.095

### GENERIC MARKING DIAGRAM



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



\* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

### SOLDERING FOOTPRINT

STYLE 1: CANCELLED	STYLE 2: PIN 1. ANODE 2. N.C. 3. CATHODE	STYLE 3: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. CATHODE
STYLE 6: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 7: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 8: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 9: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 10: PIN 1. CATHODE 2. ANODE 3. ANODE-CATHODE
				STYLE 11: PIN 1. CATHODE 2. CATHODE 3. CATHODE

<b>DOCUMENT NUMBER:</b>	<b>98ASB42819B</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>SC-70 (SOT-323)</b>	<b>PAGE 1 OF 1</b>

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

**onsemi**, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## ADDITIONAL INFORMATION

### TECHNICAL PUBLICATIONS:

Technical Library: [www.onsemi.com/design/resources/technical-documentation](http://www.onsemi.com/design/resources/technical-documentation)  
onsemi Website: [www.onsemi.com](http://www.onsemi.com)

### ONLINE SUPPORT: [www.onsemi.com/support](http://www.onsemi.com/support)

For additional information, please contact your local Sales Representative at [www.onsemi.com/support/sales](http://www.onsemi.com/support/sales)